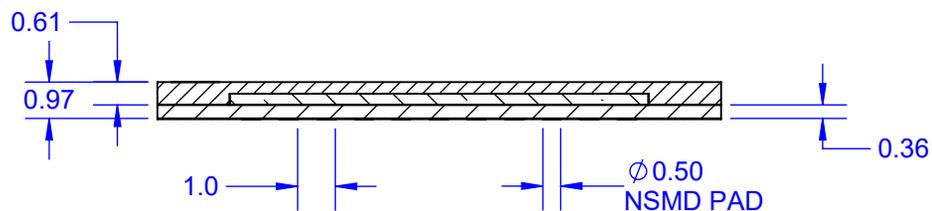
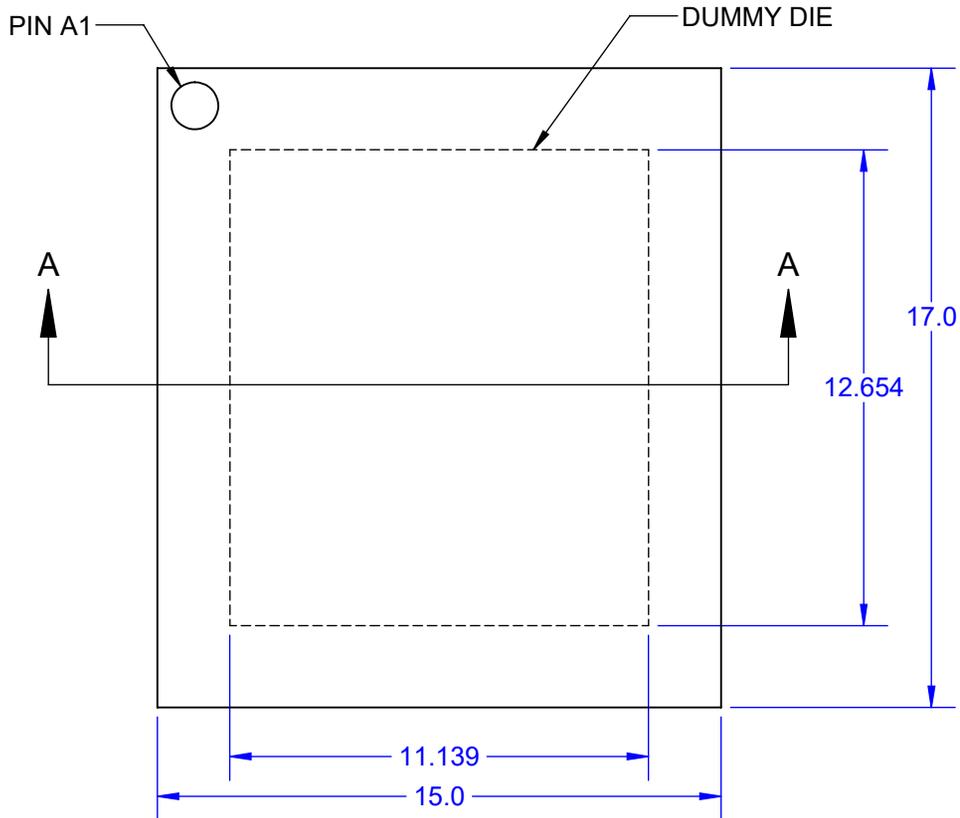


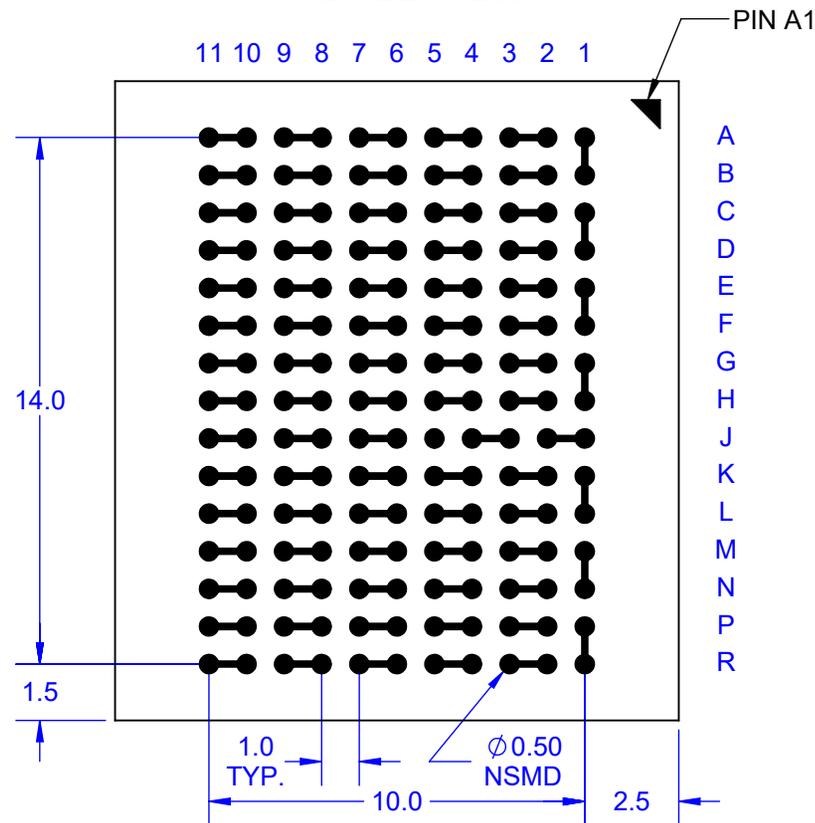
TOP VIEW



SECTION A-A

BALL ARRAY 11 x 15

BALL VIEW



Notes: (Unless Otherwise Specified).

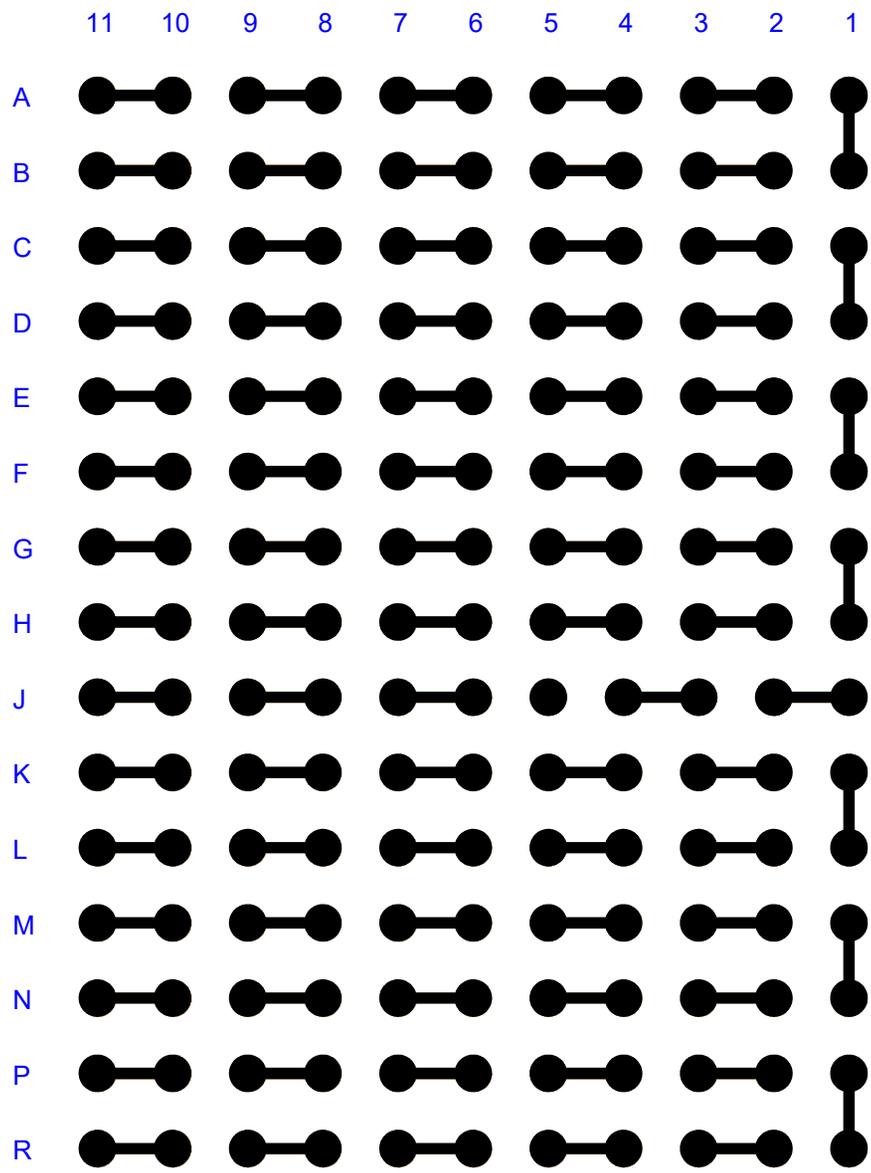
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: NONE.
- 3) BALL DIAMETER (BEFORE REFLOW): NONE.
- 4) NON-SOLDER MASK DEFINED PAD OPENING: 0.635mm (25 MIL).
- 5) COPPER PAD 0.50mm (19.7 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE 12.654 x 11.159mm (0.20~0.25mm TH).
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) SURFACE TREATMENT Ni 3.8 μ m Au 0.127 μ m OVER Cu.
- 10) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	PAD	BALL ALLOY	RoHS	Si DIE
LGA165T1.0G-DC1115D	Cu + Ni/Au	NONE	YES	YES

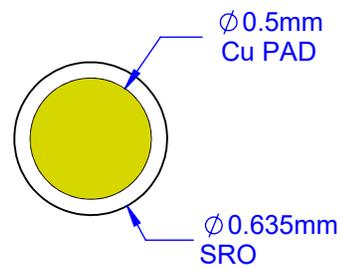
APPROVALS	DATE				
DRAWN T. Au	2/25/2022				
ENG M. Hart	2/25/2022	TITLE LGA165T1.0G-DC1115D DAISY CHAIN			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		5:1	A	515594	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 8
REVISED					

PAD VIEW



PIN A1

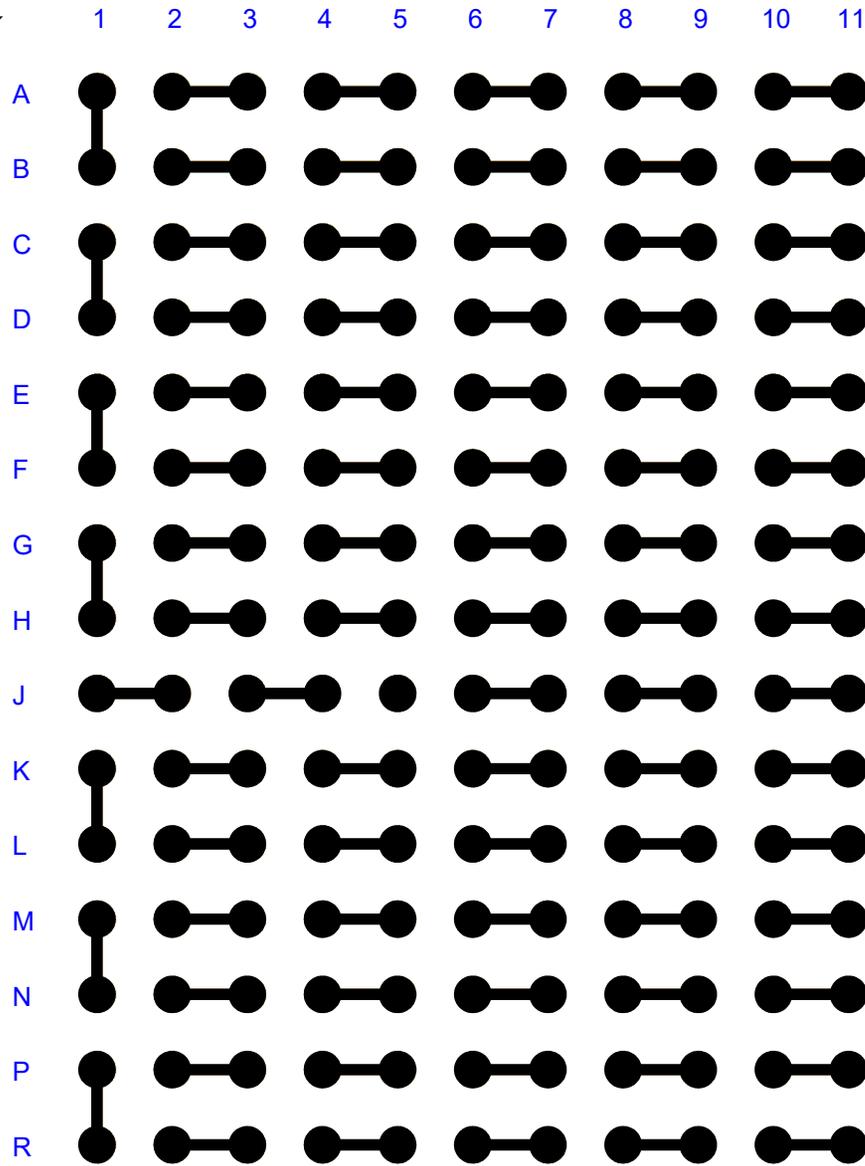
NON-SOLDER MASK DEFINED (NSMD) PAD DETAIL



TopLine[®]			
TITLE LGA165T1.0G-DC1115D DAISY CHAIN			
SCALE 10:1	SIZE A	DRAWING NO. 515594	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 8

BOTTOM SIDE (TOP X-RAY VIEW)

PIN A1 

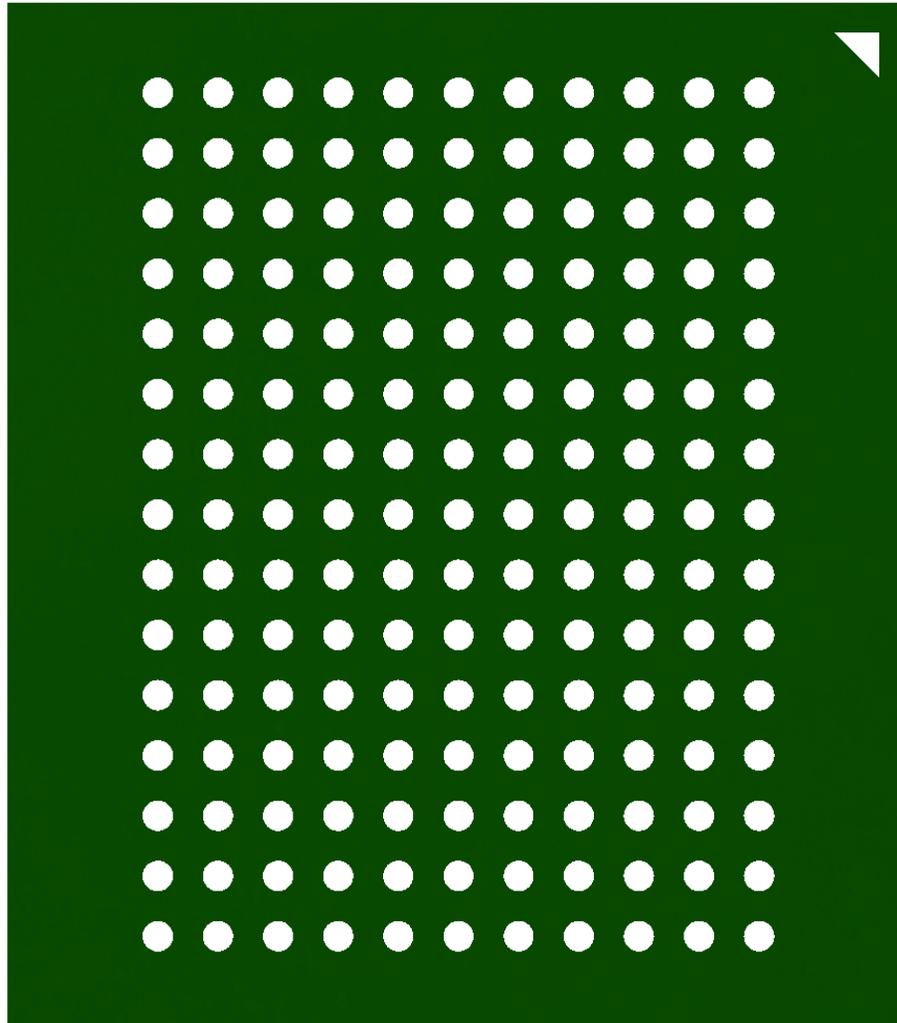


TopLine[®]			
TITLE LGA165T1.0G-DC1115D DAISY CHAIN			
SCALE	SIZE	DRAWING NO.	REV
10:1	A	515594	A
DO NOT SCALE DRAWING			SHEET 3 OF 8

**BOTTOM SOLDER MASK
(RIGHT READING)**

11 10 9 8 7 6 5 4 3 2 1

A
B
C
D
E
F
G
H
J
K
L
M
N
P
R



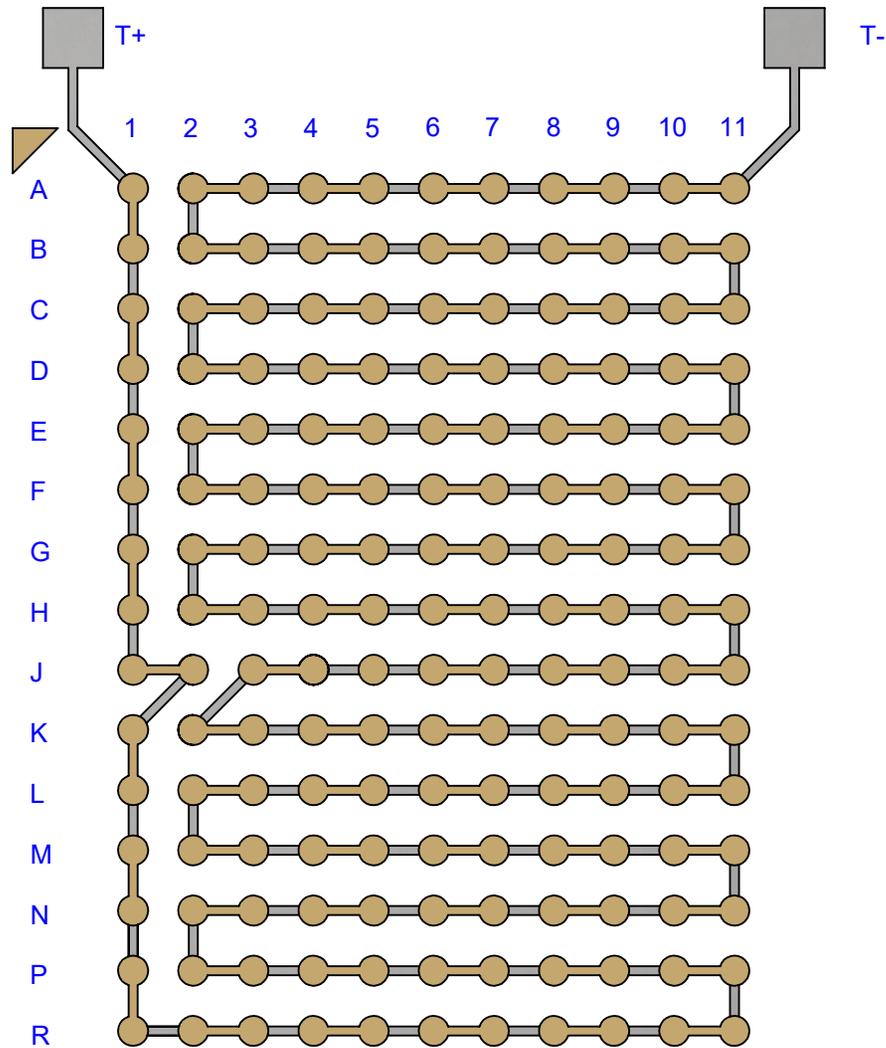
NOTES:

1. DIMENSIONS ARE IN mm.
2. SOLDER MASK OPENING $\varnothing 0.635\text{mm}$.
3. NSMD - NON SOLDER MASK PADS DEFINED.
4. Cu PAD $\varnothing 0.50\text{mm}$.
5. PAD ARRAY 11x15.

TopLine®

TITLE			
LGA165T1.0G-DC1115D DAISY CHAIN			
SCALE	SIZE	DRAWING NO.	REV
8:1	A	515594	A
DO NOT SCALE DRAWING			SHEET 4 OF 8

AFTER MOUNTING



TopLine[®]

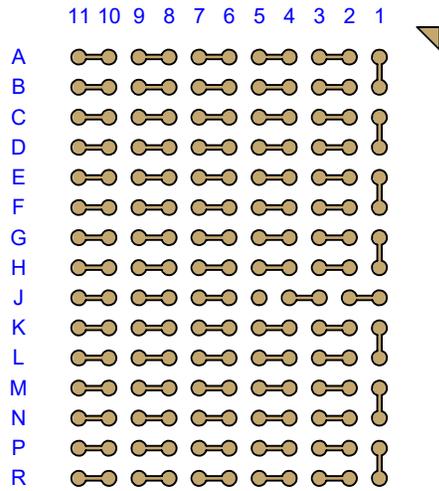
TITLE LGA165T1.0G-DC1115D
DAISY CHAIN

SCALE 8:1	SIZE A	DRAWING NO. 515594	REV A
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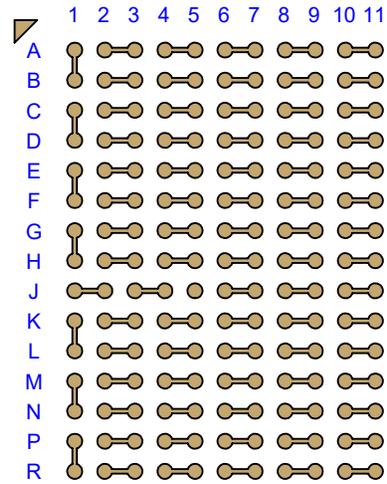
DO NOT SCALE DRAWING

SHEET 6 OF 8

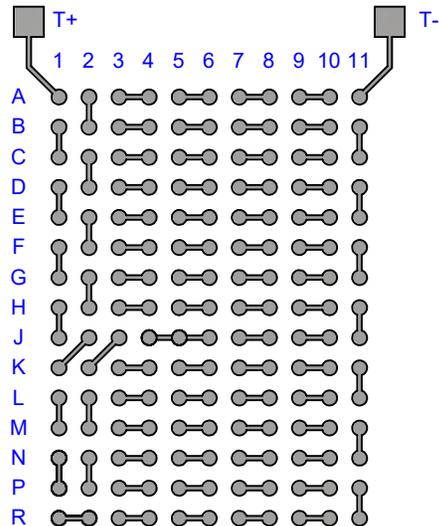
BALL VIEW



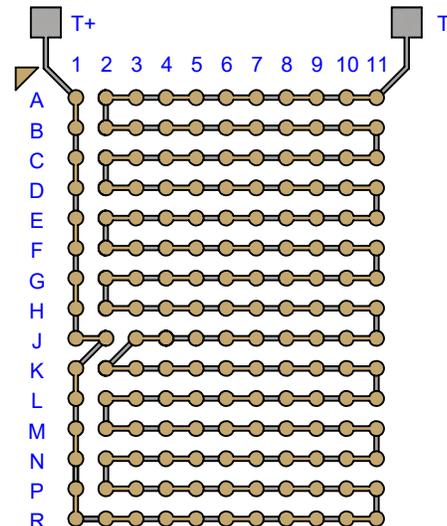
BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNT



Notes:

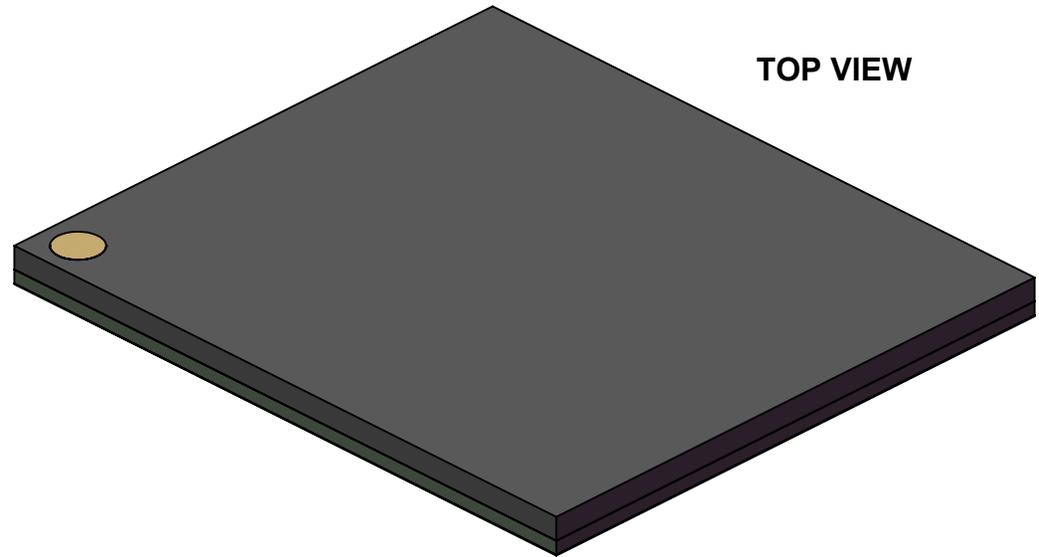
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER ϕ 0.50mm (19.7 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH ϕ 0.15mm (6 MIL).
- 4) NSMD (NON-SOLDER MASK DEFINED PAD) ϕ 0.635mm (25 MIL)

TopLine®

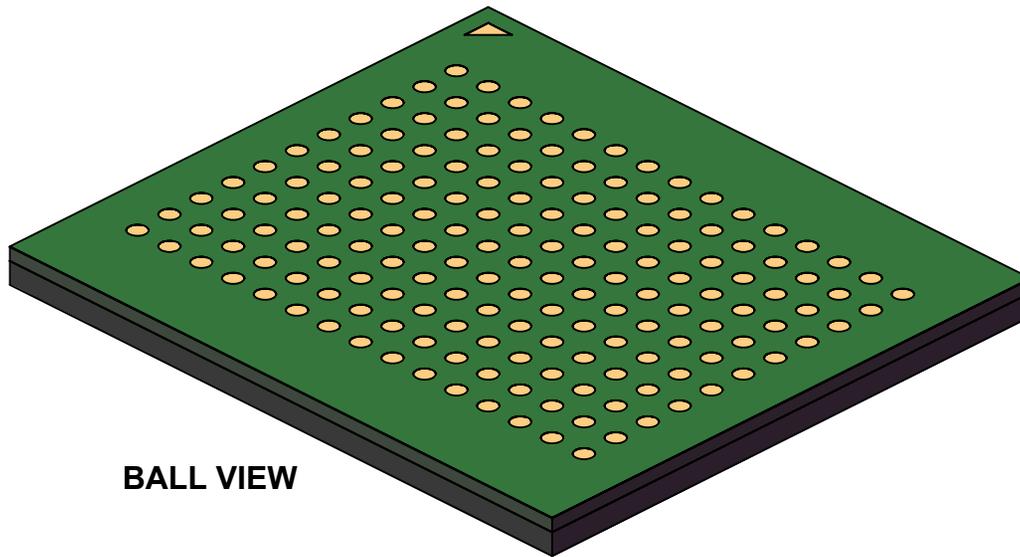
TITLE			
LGA165T1.0G-DC1115D DAISY CHAIN			
SCALE	SIZE	DRAWING NO.	REV
4:1	A	515594	A
DO NOT SCALE DRAWING			SHEET 7 OF 8

MODEL

TOP VIEW



BALL VIEW



TopLine®

TITLE LGA165T1.0G-DC1115D
DAISY CHAIN

SCALE 6:1	SIZE A	DRAWING NO. 515594	REV A
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DO NOT SCALE DRAWING

SHEET 8 OF 8